

Figure 1 shows a block diagram of the internal circuitry on the stand-alone pressure sensor chip.

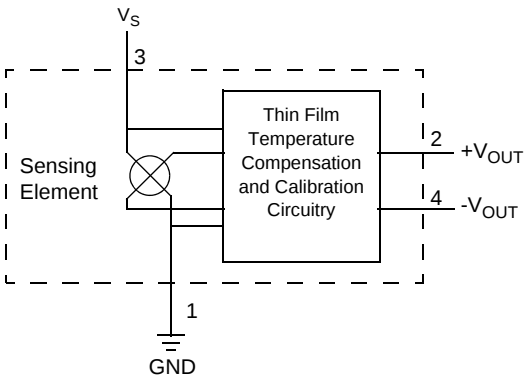


Figure 1. Temperature Compensated Pressure Sensor Schematic

Voltage Output versus Applied Differential Pressure

The differential voltage output of the sensor is directly proportional to the differential pressure applied.

The output voltage of the differential or gauge sensor increases with increasing pressure applied to the pressure side (P1) relative to the vacuum side (P2). Similarly, output voltage increases as increasing vacuum is applied to the vacuum side (P2) relative to the pressure side (P1).

Operating Characteristics

Table 1. Operating Characteristics

($V_S = 10$ Vdc, $T_A = 25^\circ\text{C}$ unless otherwise noted, $P_1 > P_2$)

Characteristics	Symbol	Min	Typ	Max	Unit
Pressure Range ⁽¹⁾	P_{OP}	0	—	50	kPa
Supply Voltage ⁽²⁾	V_S	—	10	16	Vdc
Supply Current	I_o	—	6.0	—	mAdc
Full Scale Span ⁽³⁾	V_{FSS}	38.5	40	41.5	mV
Offset ⁽⁴⁾	V_{off}	-1.0	—	1.0	mV
Sensitivity	$\Delta V/\Delta P$	—	0.8	—	mV/kPa
Linearity ⁽⁵⁾	—	-0.25	—	0.25	% V_{FSS}
Pressure Hysteresis ⁽⁵⁾ (0 to 50 kPa)	—	—	± 0.1	—	% V_{FSS}
Temperature Hysteresis ⁽⁵⁾ (-40°C to $+125^\circ\text{C}$)	—	—	± 0.5	—	% V_{FSS}
Temperature Effect on Full Scale Span ⁽⁵⁾	TCV_{FSS}	-1.0	-	1.0	% V_{FSS}
Temperature Effect on Offset ⁽⁵⁾	TCV_{off}	-1.0	-	1.0	mV
Input Impedance	Z_{in}	1000	-	2500	Ω
Output Impedance	Z_{out}	1400	-	3000	Ω
Response Time ⁽⁶⁾ (10% to 90%)	t_R	—	1.0	—	ms
Warm-Up	—	—	20	—	ms
Offset Stability ⁽⁷⁾	—	—	± 0.5	—	% V_{FSS}

1. 1.0 kPa (kiloPascal) equals 0.145 psi.

2. Device is ratiometric within this specified excitation range. Operating the device above the specified excitation range may induce additional error due to device self-heating.

3. Full Scale Span (V_{FSS}) is defined as the algebraic difference between the output voltage at full rated pressure and the output voltage at the minimum rated pressure.

4. Offset (V_{off}) is defined as the output voltage at the minimum rated pressure.

5. Accuracy (error budget) consists of the following:

Linearity: Output deviation from a straight line relationship with pressure, using end point method, over the specified pressure range.

Temperature Hysteresis: Output deviation at any temperature within the operating temperature range, after the temperature is cycled to and from the minimum or maximum operating temperature points, with zero differential pressure applied.

Pressure Hysteresis: Output deviation at any pressure within the specified range, when this pressure is cycled to and from the minimum or maximum rated pressure, at 25°C .

TcSpan: Output deviation at full rated pressure over the temperature range of 0 to 85°C , relative to 25°C .

TcOffset: Output deviation with minimum rated pressure applied, over the temperature range of 0 to 85°C , relative to 25°C .

6. Response Time is defined as the time for the incremental change in the output to go from 10% to 90% of its final value when subjected to a specified step change in pressure.

7. Offset stability is the product's output deviation when subjected to 1000 hours of Pulsed Pressure, Temperature Cycling with Bias Test.

Maximum Ratings

Table 2. Maximum Ratings⁽¹⁾

Rating	Symbol	Value	Unit
Maximum Pressure (P1 > P2)	P _{max}	200	kPa
Storage Temperature	T _{stg}	-40 to +125	°C
Operating Temperature	T _A	-40 to +125	°C

1. Exposure beyond the specified limits may cause permanent damage or degradation to the device.

LINEARITY

Linearity refers to how well a transducer's output follows the equation: $V_{out} = V_{off} + \text{sensitivity} \times P$ over the operating pressure range. There are two basic methods for calculating nonlinearity: (1) end point straight line fit (see Figure 2) or (2) a least squares best line fit. While a least squares fit gives the "best case" linearity error (lower numerical value), the calculations required are burdensome.

Conversely, an end point fit will give the "worst case" error (often more desirable in error budget calculations) and the calculations are more straightforward for the user. Motorola's specified pressure sensor linearities are based on the end point straight line method measured at the midrange pressure.

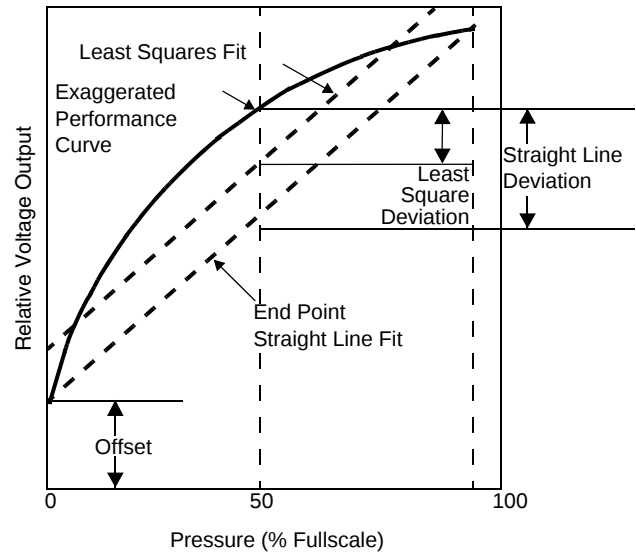


Figure 2. Linearity Specification Comparison

On-Chip Temperature Compensation and Calibration

Figure 3 shows the minimum, maximum and typical output characteristics of the MPX2050 series at 25°C. The output is directly proportional to the differential pressure and is essentially a straight line.

The effects of temperature on Full-Scale Span and Offset are very small and are shown under Operating Characteristics.

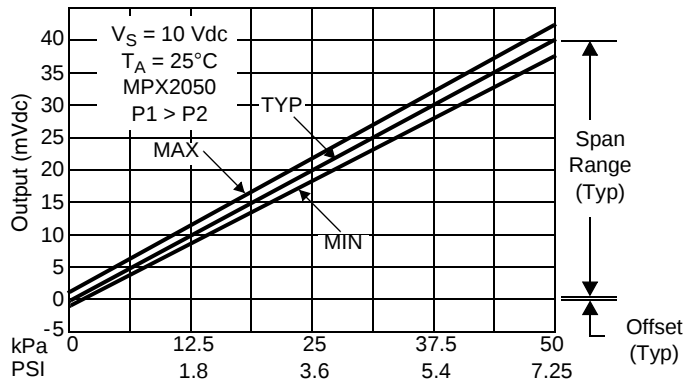


Figure 3. Output versus Pressure Differential

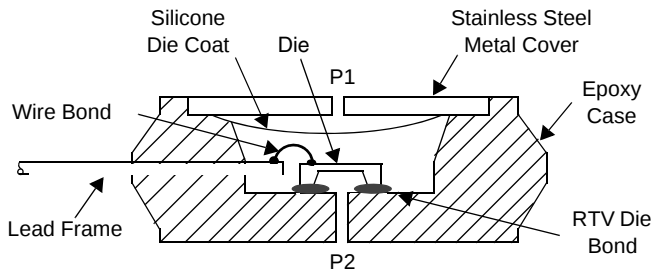


Figure 4. Cross-Sectional Diagram (not to scale)

Figure 4 illustrates the differential or gauge configuration in the basic chip carrier (Case 344). A silicone gel isolates the die surface and wire bonds from the environment, while allowing the pressure signal to be transmitted to the silicon diaphragm.

The MPX2050 series pressure sensor operating characteristics and internal reliability and qualification tests are based on use of dry air as the pressure media. Media other than dry air may have adverse effects on sensor performance and long term reliability. Contact the factory for information regarding media compatibility in your application.



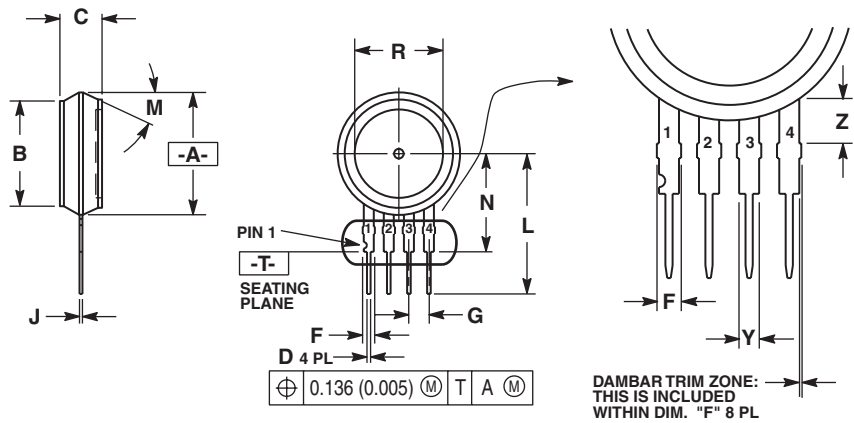
PRESSURE (P1)/VACUUM (P2) SIDE IDENTIFICATION TABLE

Freescall designates the two sides of the pressure sensor as the Pressure (P1) side and the Vacuum (P2) side. The Pressure (P1) side is the side containing the silicone gel which isolates the die. The pressure sensor is designed to operate with positive differential pressure applied, $P1 > P2$. The Pressure (P1) side may be identified by using the following table.

Table 3. Pressure (P1) Side Delineation

Part Number	Case Type	Pressure (P1) Side Identifier
MPX2050D	344	Stainless Steel Cap
MPX2050DP	344C	Side with Part Marking
MPX2050GP	344B	Side with Port Attached
MPX2050GSX	344F	Side with Port Attached

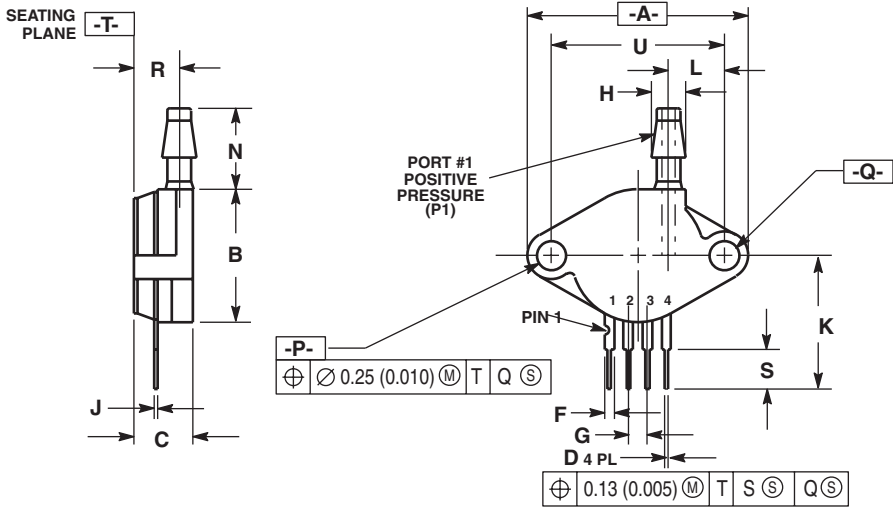
PACKAGE DIMENSIONS



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION -A- IS INCLUSIVE OF THE MOLD STOP RING. MOLD STOP RING NOT TO EXCEED 16.00 (0.630).

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.595	0.630	15.11	16.00
B	0.514	0.534	13.06	13.56
C	0.200	0.220	5.08	5.59
D	0.016	0.020	0.41	0.51
F	0.048	0.064	1.22	1.63
G	0.100 BSC		2.54 BSC	
J	0.014	0.016	0.36	0.40
L	0.695	0.725	17.65	18.42
M	30° NOM		30° NOM	
N	0.475	0.495	12.07	12.57
R	0.430	0.450	10.92	11.43
Y	0.048	0.052	1.22	1.32
Z	0.106	0.118	2.68	3.00

CASE 344-15 ISSUE AA UNIBODY PACKAGE

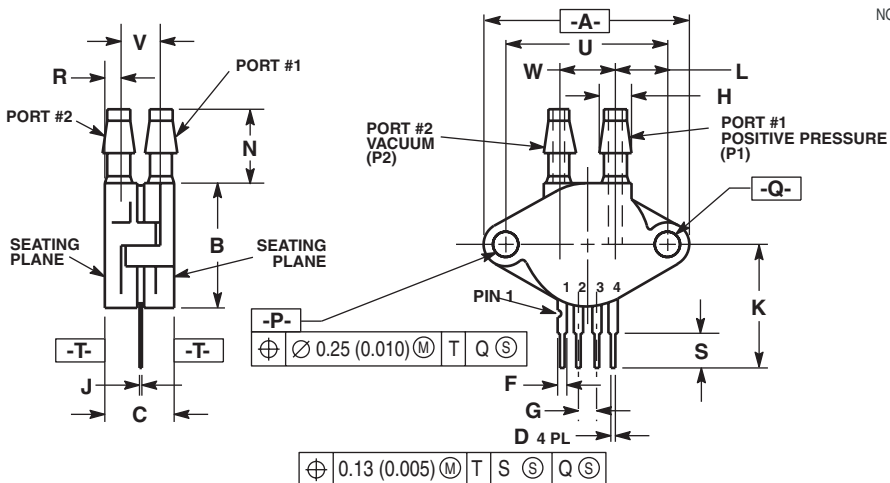


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.145	1.175	29.08	29.85
B	0.685	0.715	17.40	18.16
C	0.305	0.325	7.75	8.26
D	0.016	0.020	0.41	0.51
F	0.048	0.064	1.22	1.63
G	0.100 BSC		2.54 BSC	
H	0.182	0.194	4.62	4.93
J	0.014	0.016	0.36	0.41
K	0.695	0.725	17.65	18.42
L	0.290	0.300	7.37	7.62
N	0.420	0.440	10.67	11.18
P	0.153	0.159	3.89	4.04
Q	0.153	0.159	3.89	4.04
R	0.230	0.250	5.84	6.35
S	0.220	0.240	5.59	6.10
U	0.910 BSC		23.11 BSC	

CASE 344B-01 ISSUE B UNIBODY PACKAGE

PACKAGE DIMENSIONS

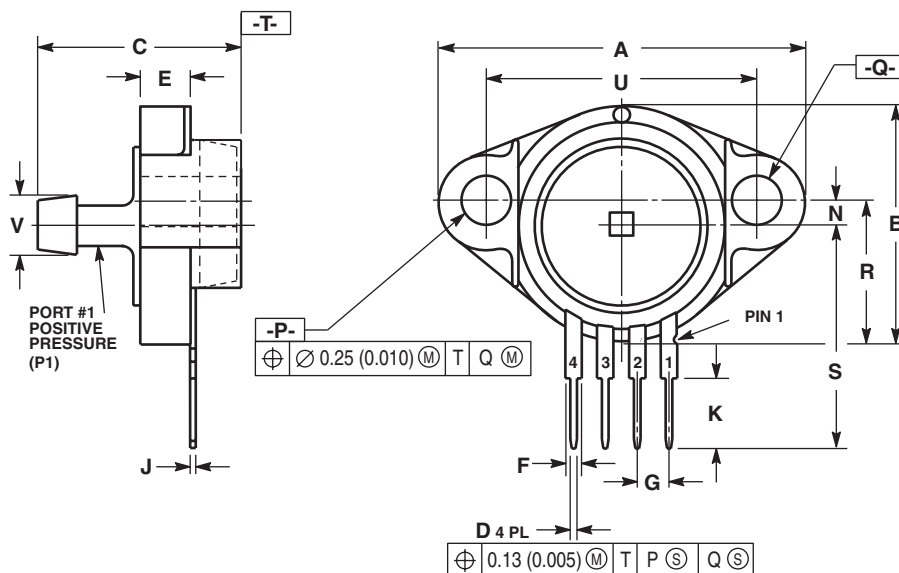


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.145	1.175	29.08	29.85
B	0.685	0.715	17.40	18.16
C	0.405	0.435	10.29	11.05
D	0.016	0.020	0.41	0.51
F	0.048	0.064	1.22	1.63
G	0.100 BSC		2.54 BSC	
H	0.182	0.194	4.62	4.93
J	0.014	0.016	0.36	0.41
K	0.695	0.725	17.65	18.42
L	0.290	0.300	7.37	7.62
N	0.420	0.440	10.67	11.18
P	0.153	0.159	3.89	4.04
Q	0.153	0.159	3.89	4.04
R	0.063	0.083	1.60	2.11
S	0.220	0.240	5.59	6.10
U	0.910 BSC		23.11 BSC	
V	0.248	0.278	6.30	7.06
W	0.310	0.330	7.87	8.38

- STYLE 1:
1. GROUND
 2. + OUTPUT
 3. + SUPPLY
 4. - OUTPUT

CASE 344C-01 ISSUE B UNIBODY PACKAGE



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.080	1.120	27.43	28.45
B	0.740	0.760	18.80	19.30
C	0.630	0.650	16.00	16.51
D	0.016	0.020	0.41	0.51
E	0.160	0.180	4.06	4.57
F	0.048	0.064	1.22	1.63
G	0.100 BSC		2.54 BSC	
J	0.014	0.016	0.36	0.41
K	0.220	0.240	5.59	6.10
N	0.070	0.080	1.78	2.03
P	0.150	0.160	3.81	4.06
Q	0.150	0.160	3.81	4.06
R	0.440	0.460	11.18	11.68
S	0.695	0.725	17.65	18.42
U	0.840	0.860	21.34	21.84
V	0.182	0.194	4.62	4.92

- STYLE 1:
1. GROUND
 2. V (+) OUT
 3. V SUPPLY
 4. V (-) OUT

CASE 344F-01 ISSUE B UNIBODY PACKAGE

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